

SOT1160-1

plastic, extremely thin quad flat package; no leads; 10 terminals; 0.4 mm pitch; 1.4 mm x 1.8 mm x 0.5 mm body

9 January 2017

Package information

1. Package summary

Dimensions (mm)	1.4 x 1.8 x 0.5
Terminal position code	Q (quad)
Package type descriptive code	XQFN10
Package outline version code	SOT1160-1
Manufacturer package code	SOT1160
Package type industry code	XQFN10
Package outline version description	plastic, extremely thin quad flat package; no leads; 10 terminals; 0.4 mm pitch; 1.4 mm x 1.8 mm x 0.5 mm body
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package body material type	P
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	IC26_CHAPTER_6_2000
Mounting method type	S (surface mount)
Generic mounting and soldering information	AN10365_3
Package life cycle status	REL
Major version date	12-4-2010
Minor version date	10-5-2012
Security status	COMPANY PUBLIC
Modified date	15-11-2012
Issue date	29-12-2009
Web publication date	28-11-2012
Initial web publication date	18-1-2011
Customer specific indicator	N
Maturity	Product
Package author	Nair Deepa
Package approver	Nair Deepa

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A	seated height	-	-	-	0.5	mm



plastic, extremely thin quad flat package; no leads; 10 terminals; 0.4 mm pitch; 1.4 mm x 1.8 mm x 0.5 mm body

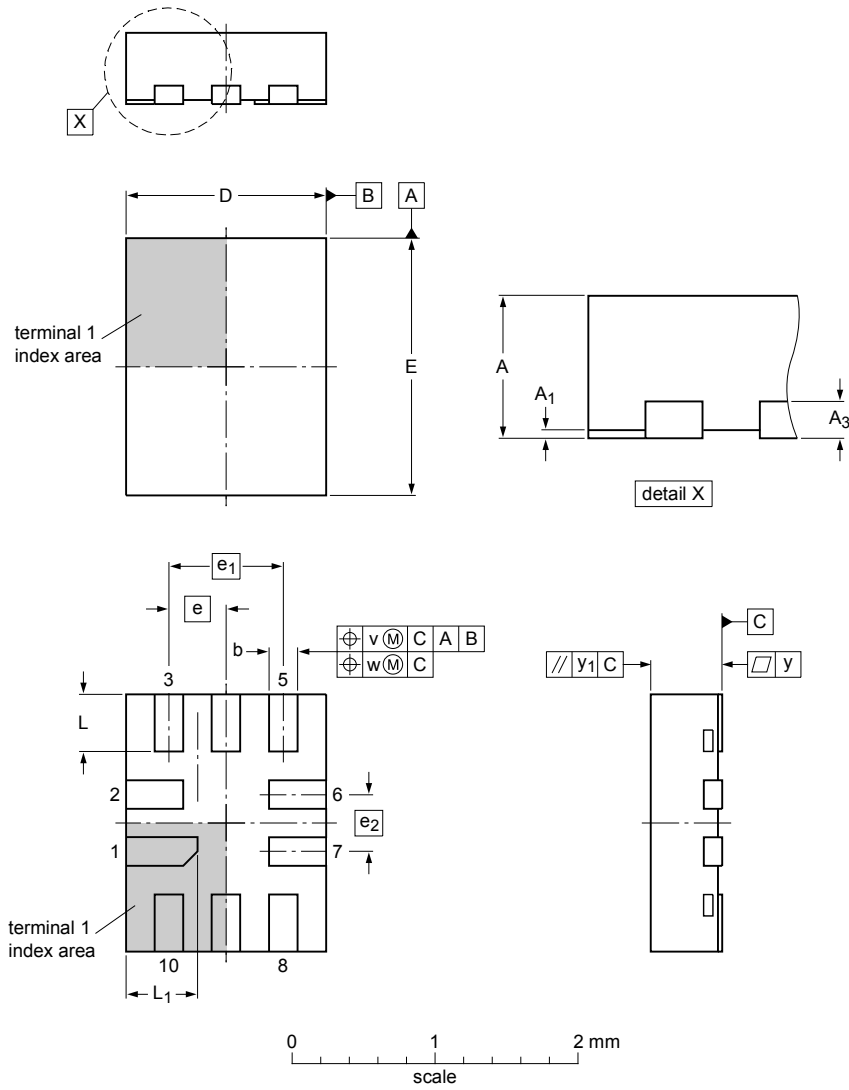
Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.3	-	1.4	1.5	mm
E	package width		1.7	-	1.8	1.9	mm
e	nominal pitch		-	-	0.4	-	mm
n ₂	actual quantity of termination		-	-	10	-	

plastic, extremely thin quad flat package; no leads; 10 terminals; 0.4 mm pitch; 1.4 mm x 1.8 mm x 0.5 mm body

2. Package outline

XQFN10: plastic, extremely thin quad flat package; no leads; 10 terminals; body 1.40 x 1.80 x 0.50 mm

SOT1160-1



Dimensions

Unit ⁽¹⁾	A	A ₁	A ₃	b	D	E	e	e ₁	e ₂	L	L ₁	v	w	y	y ₁
max	0.5	0.05		0.25	1.5	1.9				0.45	0.55				
mm nom			0.127	0.20	1.4	1.8	0.4	0.8	0.4	0.40	0.50	0.1	0.05	0.05	0.05
min		0.00		0.15	1.3	1.7				0.35	0.45				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sof1160-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1160-1	---	---	---		09-12-28 09-12-29

Fig. 1. Package outline XQFN10 (SOT1160-1)

plastic, extremely thin quad flat package; no leads; 10 terminals; 0.4 mm pitch; 1.4 mm x 1.8 mm x 0.5 mm body

3. Soldering

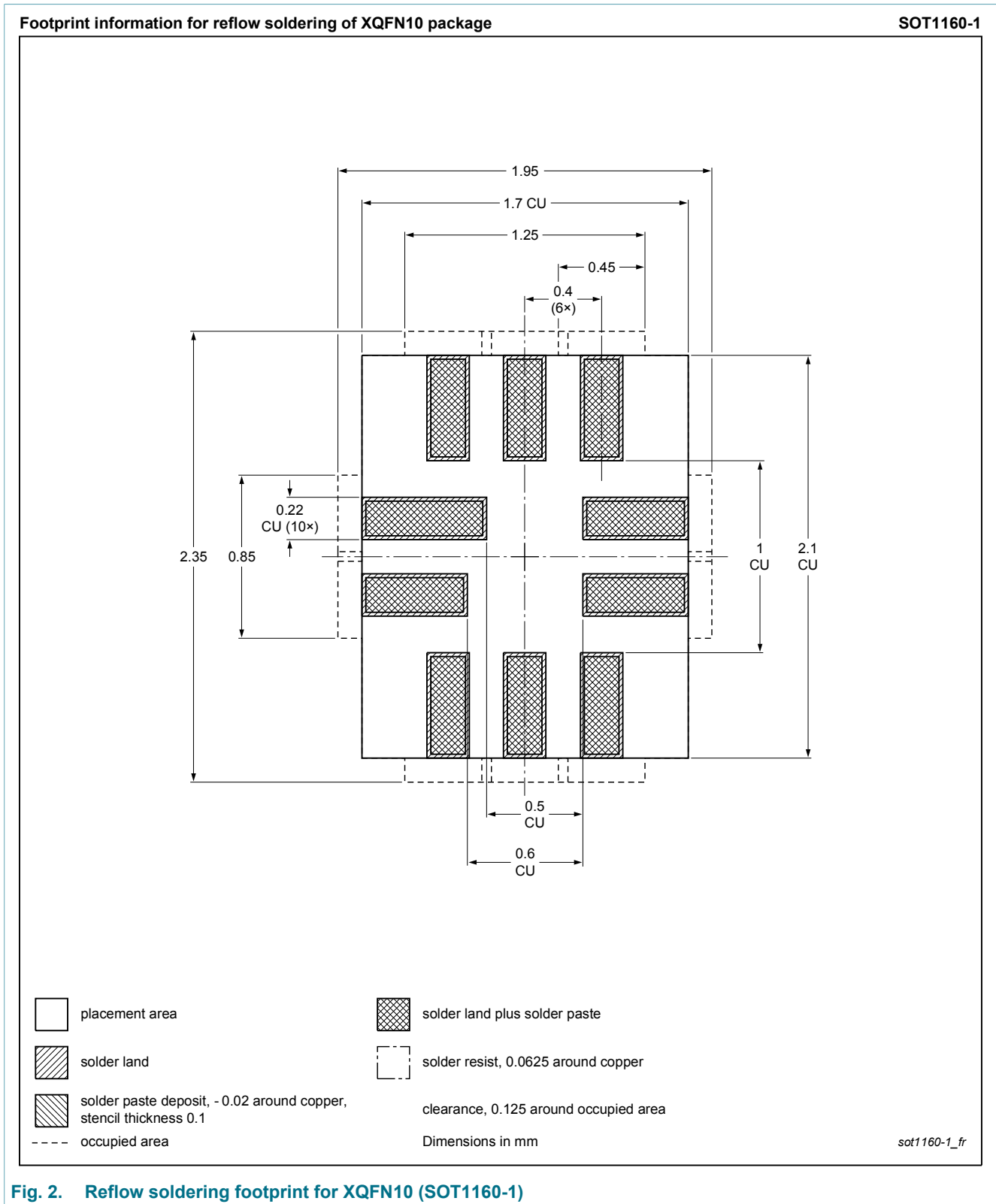


Fig. 2. Reflow soldering footprint for XQFN10 (SOT1160-1)

plastic, extremely thin quad flat package; no leads; 10 terminals; 0.4 mm pitch; 1.4 mm x 1.8 mm x 0.5 mm body

4. Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the *Terms and conditions of commercial sale* of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

plastic, extremely thin quad flat package; no leads; 10 terminals; 0.4 mm pitch; 1.4 mm x 1.8 mm x 0.5 mm body

5. Contents

1. Package summary.....	1
2. Package outline.....	3
3. Soldering.....	4
4. Legal information.....	5

© NXP Semiconductors N.V. 2017. All rights reserved

For more information, please visit: <http://www.nxp.com>
For sales office addresses, please send an email to: salesaddresses@nxp.com
Date of release: 9 January 2017
